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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	185000
Number of Logic Elements/Cells	490000
Total RAM Bits	46080000
Number of I/O	552
Number of Gates	-
Voltage - Supply	0.82V ~ 0.88V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxea5h3f35i3ln

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Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed	Core Speed Grade										
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I3YY	14			
3 GX channel—8.5 Gbps	_	Yes	Yes	Yes	_	Yes	Yes ⁽⁴⁾	Yes			

Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.
- (3) C2L, I2L, and I3L speed grades are for low-power devices.
- (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transacius Snood Crada		Core Speed Grade							
Transceiver Speed Grade	C1	C2	12	13					
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_					
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes					

Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

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			Re	esistance	Tolerance	,	
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%
50-Ω R _S	Internal series termination without calibration (50- Ω setting)	V _{CCIO} = 1.2 V	±35	±35	±50	±50	%
100-Ω R _D	Internal differential termination (100-Ω setting)	V _{CCPD} = 2.5 V	±25	±25	±25	±25	%

Calibration accuracy for the calibrated series and parallel OCTs are applicable at the moment of calibration. When voltage and temperature conditions change after calibration, the tolerance may change.

OCT calibration is automatically performed at power-up for OCT-enabled I/Os. Table 13 lists the OCT variation with temperature and voltage after power-up calibration. Use Table 13 to determine the OCT variation after power-up calibration and Equation 1 to determine the OCT variation without recalibration.

Equation 1. OCT Variation Without Recalibration for Stratix V Devices (1), (2), (3), (4), (5), (6)

$$R_{OCT} = R_{SCAL} \Big(1 + \langle \frac{dR}{dT} \times \Delta T \rangle \pm \langle \frac{dR}{dV} \times \Delta V \rangle \Big)$$

Notes to Equation 1:

- (1) The R_{OCT} value shows the range of OCT resistance with the variation of temperature and V_{CCIO} .
- (2) R_{SCAL} is the OCT resistance value at power-up.
- (3) ΔT is the variation of temperature with respect to the temperature at power-up.
- (4) ΔV is the variation of voltage with respect to the V_{CCIO} at power-up.
- (5) dR/dT is the percentage change of R_{SCAL} with temperature.
- (6) dR/dV is the percentage change of R_{SCAL} with voltage.

Table 13 lists the on-chip termination variation after power-up calibration.

Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 1 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit
		3.0	0.0297	
	007	2.5	0.0344	
dR/dV	OCT variation with voltage without recalibration	1.8	0.0499	%/mV
	Todanstation	1.5	0.0744	
		1.2	0.1241	

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Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 2 of 2)

I/O				V _{DIF(}	_{DC)} (V)	V _{X(AC)} (V)			V _{CM(DC)} (V)			V _{DIF(AC)} (V)	
Standard	Min	Тур	Max	Min	Max	Min	Тур	Max	Min	Тур	Max	Min	Max
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	V _{CCIO} + 0.3	_	0.5* V _{CCIO}	_	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.3	V _{CCIO} + 0.48
HSUL-12	1.14	1.2	1.3	0.26	0.26	0.5*V _{CCIO} - 0.12	0.5* V _{CCIO}	0.5*V _{CCIO} + 0.12	0.4* V _{CCIO}	0.5* V _{CCIO}	0.6* V _{CCIO}	0.44	0.44

Table 22. Differential I/O Standard Specifications for Stratix V Devices (7)

I/O	V _{CCIO} (V) ⁽¹⁰⁾				V _{ID} (mV) ⁽⁸⁾		V _{ICM(DC)} (V)			V _{OD} (V) ⁽⁶⁾			V _{OCM} (V) ⁽⁶⁾		
Standard	Min	Тур	Max	Min	Condition	Max	Min	Condition	Max	Min	Тур	Max	Min	Тур	Max
PCML	Trar	Transmitter, receiver, and input reference clock pins of the high-speed transceivers use the PCML I/O standard. For transmitter, receiver, and reference clock I/O pin specifications, refer to Table 23 on page 18.													
2.5 V	2.375	2.5	2.625	100	V _{CM} =	_	0.05	D _{MAX} ≤ 700 Mbps	1.8	0.247	_	0.6	1.125	1.25	1.375
LVDS (1)	2.373	2.3	2.023	100	1.25 V		1.05	D _{MAX} > 700 Mbps	1.55	0.247	_	0.6	1.125	1.25	1.375
BLVDS (5)	2.375	2.5	2.625	100	_	_	_	_	_	_	_	_	_	_	_
RSDS (HIO) ⁽²⁾	2.375	2.5	2.625	100	V _{CM} = 1.25 V	_	0.3	_	1.4	0.1	0.2	0.6	0.5	1.2	1.4
Mini- LVDS (HIO) (3)	2.375	2.5	2.625	200	_	600	0.4	_	1.325	0.25	_	0.6	1	1.2	1.4
LVPECL (4	_	_	_	300	_	_	0.6	D _{MAX} ≤ 700 Mbps	1.8	_	_	_	_	_	_
), (9)	_	_	_	300	_	_	1	D _{MAX} > 700 Mbps	1.6	_	_	_	_	_	_

Notes to Table 22:

- (1) For optimized LVDS receiver performance, the receiver voltage input range must be between 1.0 V to 1.6 V for data rates above 700 Mbps, and 0 V to 1.85 V for data rates below 700 Mbps.
- (2) For optimized RSDS receiver performance, the receiver voltage input range must be between 0.25 V to 1.45 V.
- (3) For optimized Mini-LVDS receiver performance, the receiver voltage input range must be between 0.3 V to 1.425 V.
- (4) For optimized LVPECL receiver performance, the receiver voltage input range must be between 0.85 V to 1.75 V for data rate above 700 Mbps and 0.45 V to 1.95 V for data rate below 700 Mbps.
- (5) There are no fixed V_{ICM} , V_{OD} , and V_{OCM} specifications for BLVDS. They depend on the system topology.
- (6) RL range: $90 \le RL \le 110 \Omega$.
- (7) The 1.4-V and 1.5-V PCML transceiver I/O standard specifications are described in "Transceiver Performance Specifications" on page 18.
- (8) The minimum VID value is applicable over the entire common mode range, VCM.
- (9) LVPECL is only supported on dedicated clock input pins.
- (10) Differential inputs are powered by VCCPD which requires 2.5 $\rm V.$

Power Consumption

Altera offers two ways to estimate power consumption for a design—the Excel-based Early Power Estimator and the Quartus[®] II PowerPlay Power Analyzer feature.

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description Conditions	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_	_	_	10	_	_	10	_	_	10	μs

Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{I TD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll\ powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{nll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{REF} is 2000 Ω ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

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Table 26 shows the approximate maximum data rate using the 10G PCS.

Table 26. Stratix V 10G PCS Approximate Maximum Data Rate (1)

Mode ⁽²⁾	Transceiver	PMA Width	64	40	40	40	32	32			
Widue (2)	Speed Grade	PCS Width	64	66/67	50	40	64/66/67	32			
	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6			
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5			
	۷	C3, I3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88			
FIFO or Register		C1, C2, C2L, I2, I2L core speed grade									
	3	C3, I3, I3L core speed grade	8.5 Gbps								
	3	C4, I4 core speed grade									
		I3YY core speed grade			10.312	25 Gbps					

Notes to Table 26:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive Speed Grade		S	Unit					
Description		Min	Тур	Max	Min	Тур	Max	5			
Reference Clock	l		<u>I</u>	U.			<u>I</u>	<u>I</u>			
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	1.2-V PCML, 1.4-V PCML, 1.5-V PCML, 2.5-V PCML, Differential LVPECL, LV and HCSL								
otandardo	RX reference clock pin	1.4-V PCML, 1.5-V PCML, 2.5-V PCML, LVPECL, and LVDS									
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz			
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz			
Rise time	20% to 80%	_	_	400	_	_	400				
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps			
Duty cycle	_	45	_	55	45	_	55	%			
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz			
Spread-spectrum downspread	PCle		0 to -0.5	_	_	0 to -0.5	_	%			
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω			
Absolute V _{MAX} (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V			
	RX reference clock pin	_	_	1.2	_	_	1.2				
Absolute V _{MIN}	_	-0.4	_	_	-0.4		_	V			
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV			
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000	2)	1	050/1000	2)	mV			
	RX reference clock pin	1	.0/0.9/0.85	(22)	1.	0/0.9/0.85	(22)	V			
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV			

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 2 of 5) $^{(1)}$

Symbol/	Conditions	S	Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	1
	100 Hz	_	_	-70	_	_	-70	
Transmitter REFCLK	1 kHz	_	_	-90		_	-90	
Phase Noise (622	10 kHz	_	_	-100	_	_	-100	dBc/Hz
MHz) ⁽¹⁸⁾	100 kHz	_	_	-110	_	_	-110	
	≥1 MHz		_	-120	_		-120	1
Transmitter REFCLK Phase Jitter (100 MHz) ⁽¹⁵⁾	10 kHz to 1.5 MHz (PCle)	_	_	3	_	_	3	ps (rms)
RREF (17)	_	_	1800 ± 1%	_	_	1800 ± 1%	_	Ω
Transceiver Clocks								
fixedclk clock frequency	PCIe Receiver Detect	_	100 or 125	_	_	100 or 125	_	MHz
Reconfiguration clock (mgmt_clk_clk) frequency		100	_	125	100		125	MHz
Receiver								
Supported I/O Standards	_		1.4-V PCML	, 1.5-V PCML	_, 2.5-V PCI	ML, LVPEC	L, and LVDS	6
Data rate (Standard PCS) (21)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS) (21)	GX channels	600	_	12,500	600	_	12,500	Mbps
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Absolute V _{MAX} for a receiver pin ⁽³⁾	GT channels	_	_	1.2		_	1.2	V
Absolute V _{MIN} for a receiver pin	GT channels	-0.4	_	_	-0.4	_	_	V
Maximum peak-to-peak	GT channels		_	1.6	_		1.6	V
differential input voltage V _{ID} (diff p-p) before device configuration ⁽²⁰⁾	GX channels				(8)			
	GT channels							
Maximum peak-to-peak differential input voltage V _{ID} (diff p-p) after device configuration (16), (20)	$V_{CCR_GTB} = 1.05 \text{ V} $ $(V_{ICM} = 0.65 \text{ V})$	_	_	2.2	_	_	2.2	V
oomiguration ', ' /	GX channels				(8)		•	•
Minimum differential	GT channels	200	_	_	200		_	mV
eye opening at receiver serial input pins ⁽⁴⁾ , ⁽²⁰⁾	GX channels				(8)			

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5) $^{(1)}$

Symbol/	Conditions		Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Differential on-chip	GT channels	_	100	_		100	<u> </u>	Ω
termination resistors	GX channels			•	(8)		<u>'</u>	
\/	GT channels	_	500	_	_	500	_	mV
V _{OCM} (AC coupled)	GX channels			•	(8)		<u>'</u>	
Diag/Fall time	GT channels	_	15	_	_	15	_	ps
Rise/Fall time	GX channels		<u>I</u>		(8)			
Intra-differential pair skew	GX channels				(8)			
Intra-transceiver block transmitter channel-to- channel skew	GX channels				(8)			
Inter-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
CMU PLL								
Supported Data Range	_	600	_	12500	600	_	8500	Mbps
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs
ATX PLL								
	VCO post- divider L=2	8000	_	12500	8000	_	8500	Mbps
	L=4	4000	_	6600	4000	_	6600	Mbps
Supported Data Rate	L=8	2000	_	3300	2000	_	3300	Mbps
Range for GX Channels	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	_	14025	9800	_	12890	Mbps
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs
fPLL			•					
Supported Data Range	_	600	_	3250/ 3.125 ⁽²³⁾	600	_	3250/ 3.125 ⁽²³⁾	Mbps
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs

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Figure 4 shows the differential transmitter output waveform.

Figure 4. Differential Transmitter/Receiver Output/Input Waveform

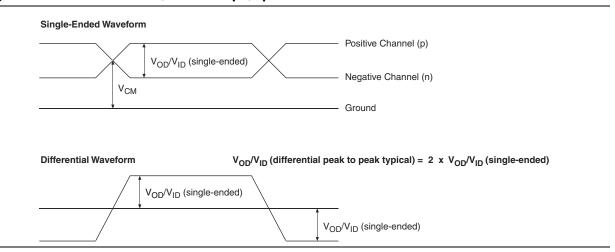


Figure 5 shows the Stratix V AC gain curves for GT channels.

Figure 5. AC Gain Curves for GT Channels

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Table 42. Memory Output Clock Jitter Specification for Stratix V Devices (1), (Part 2 of 2) (2), (3)

Clock Network	Parameter	Symbol	C	1	C2, C2L	, I2 , I2L	C3, I3	3, I3L, YY	C4	,14	Unit
NEIWUIK			Min	Max	Min	Max	Min	Max	Min	Max	
	Clock period jitter	$t_{\text{JIT(per)}}$	-25	25	-25	25	-30	30	-35	35	ps
PHY Clock	Cycle-to-cycle period jitter	t _{JIT(cc)}	-50	50	-50	50	-60	60	-70	70	ps
	Duty cycle jitter	$t_{JIT(duty)}$	-37.5	37.5	-37.5	37.5	-45	45	-56	56	ps

Notes to Table 42:

- (1) The clock jitter specification applies to the memory output clock pins generated using differential signal-splitter and DDIO circuits clocked by a PLL output routed on a PHY, regional, or global clock network as specified. Altera recommends using PHY clock networks whenever possible.
- (2) The clock jitter specification applies to the memory output clock pins clocked by an integer PLL.
- (3) The memory output clock jitter is applicable when an input jitter of 30 ps peak-to-peak is applied with bit error rate (BER) -12, equivalent to 14 sigma.

OCT Calibration Block Specifications

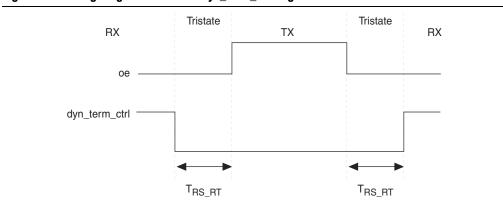
Table 43 lists the OCT calibration block specifications for Stratix V devices.

Table 43. OCT Calibration Block Specifications for Stratix V Devices

Symbol	Description	Min	Тур	Max	Unit
OCTUSRCLK	Clock required by the OCT calibration blocks	_	_	20	MHz
T _{OCTCAL}	Number of OCTUSRCLK clock cycles required for OCT $\ensuremath{R}_{\ensuremath{S}}/\ensuremath{R}_{\ensuremath{T}}$ calibration		1000	_	Cycles
T _{OCTSHIFT}	Number of OCTUSRCLK clock cycles required for the OCT code to shift out		32	_	Cycles
T _{RS_RT}	Time required between the $\mathtt{dyn_term_ctrl}$ and oe signal transitions in a bidirectional I/O buffer to dynamically switch between OCT R_S and R_T (Figure 10)	_	2.5	_	ns

Figure 10 shows the timing diagram for the oe and dyn term ctrl signals.

Figure 10. Timing Diagram for oe and dyn_term_ctrl Signals



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Table 46.	JTAG Timino	Parameters ar	nd Values	for Stratix V Devices
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Symbol	Description	Min	Max	Unit
t _{JPH}	JTAG port hold time	5	_	ns
t _{JPCO}	JTAG port clock to output	_	11 ⁽¹⁾	ns
t _{JPZX}	JTAG port high impedance to valid output	_	14 ⁽¹⁾	ns
t _{JPXZ}	JTAG port valid output to high impedance	_	14 ⁽¹⁾	ns

Notes to Table 46:

- (1) A 1 ns adder is required for each V_{CCIO} voltage step down from 3.0 V. For example, t_{JPCO} = 12 ns if V_{CCIO} of the TDO I/O bank = 2.5 V, or 13 ns if it equals 1.8 V.
- (2) The minimum TCK clock period is 167 ns if VCCBAT is within the range 1.2V-1.5V when you perform the volatile key programming.

Raw Binary File Size

For the POR delay specification, refer to the "POR Delay Specification" section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices".

Table 47 lists the uncompressed raw binary file (.rbf) sizes for Stratix V devices.

Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)
	ECCVAO	H35, F40, F35 ⁽²⁾	213,798,880	562,392
	5SGXA3	H29, F35 ⁽³⁾	137,598,880	564,504
	5SGXA4	_	213,798,880	563,672
	5SGXA5	_	269,979,008	562,392
	5SGXA7	_	269,979,008	562,392
Stratix V GX	5SGXA9	_	342,742,976	700,888
	5SGXAB	_	342,742,976	700,888
	5SGXB5	_	270,528,640	584,344
	5SGXB6	_	270,528,640	584,344
	5SGXB9	_	342,742,976	700,888
	5SGXBB	_	342,742,976	700,888
Chrotin V CT	5SGTC5	_	269,979,008	562,392
Stratix V GT	5SGTC7	_	269,979,008	562,392
	5SGSD3	_	137,598,880	564,504
	FCCCD4	F1517	213,798,880	563,672
Ctrativ V CC	5SGSD4	_	137,598,880	564,504
Stratix V GS	5SGSD5	_	213,798,880	563,672
	5SGSD6	_	293,441,888	565,528
	5SGSD8	_	293,441,888	565,528

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Table 49. DCLK-to-DATA[] Ratio (1) (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
EDD22	Disabled	Enabled	4
FPP ×32	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

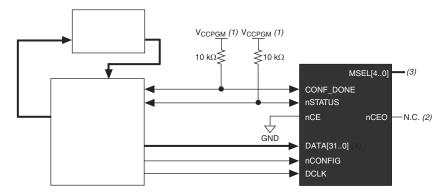
(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio -1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM}.
- (2) You can leave the nceo pin unconnected or use it as a user I/O pin when it does not feed another device's nce pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP $\times 8$, use DATA [7..0]. If you use FPP $\times 16$, use DATA [15..0].

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Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μ\$
t _{CF2ST1}	nCONFIG high to nSTATUS high	_	1,506 ⁽³⁾	μ\$
t _{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μ\$
t _{ST2CK} (6)	nSTATUS high to first rising edge of DCLK	2	_	μ\$
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _{CD2UM}	CONF_DONE high to user mode (4)	175	437	μS
+	GOVER DOVER high to GUVERN anabled	4 × maximum		
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁵⁾	_	_

Notes to Table 50:

- (1) Use these timing parameters when the decompression and design security features are disabled.
- (2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value is applicable if you do not delay configuration by externally holding the nstatus low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

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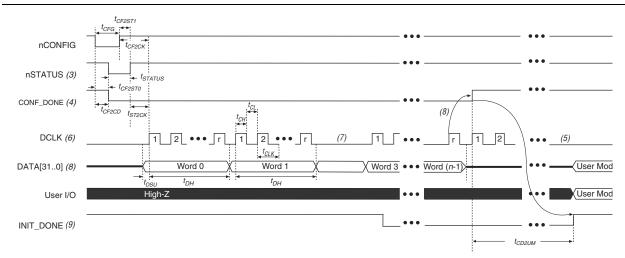


Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)

Notes to Figure 13:

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nconfig, nstatus, and conf_done are at logic high levels. When nconfig is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1 $^{(1)}$

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nconfig low to conf_done low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nconfig high to nstatus high	_	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} (5)	nstatus high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	N-1/f _{DCLK} ⁽⁵⁾	_	S
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _R	Input rise time	_	40	ns
t _F	Input fall time	_	40	ns
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and f_{DCLK} is the DCLK frequency the system is operating.
- (6) If nstatus is monitored, follow the t_{status} specification. If nstatus is not monitored, follow the t_{cfack} specification.

Page 64 I/O Timing

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
t _{RU_nCONFIG} (1)	250	_	ns
t _{RU_nRSTIMER} (2)	250	_	ns

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units
5.3	7.9	12.5	MHz

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Doromotor	Avoilable	weilehle Min	Fast Model		Slow Model							
Parameter (1)	Available Settings	Offset (2)	Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

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Table 58. IOE Programmable Delay for Stratix V Devices (Part 2 of 2)

Parameter	Available	Min Offset	Fast Model		Slow Model							
(1)	Settings		Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D3	8	0	1.587	1.699	2.793	2.793	2.992	3.192	2.811	3.047	3.257	ns
D4	64	0	0.464	0.492	0.838	0.838	0.924	1.011	0.843	0.920	1.006	ns
D5	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D6	32	0	0.229	0.244	0.415	0.415	0.458	0.503	0.418	0.456	0.499	ns

Notes to Table 58:

- (1) You can set this value in the Quartus II software by selecting D1, D2, D3, D5, and D6 in the Assignment Name column of Assignment Editor.
- (2) Minimum offset does not include the intrinsic delay.

Programmable Output Buffer Delay

Table 59 lists the delay chain settings that control the rising and falling edge delays of the output buffer. The default delay is 0 ps.

Table 59. Programmable Output Buffer Delay for Stratix V Devices (1)

Symbol	Parameter	Typical	Unit	
		0 (default)	ps	
D	Rising and/or falling edge delay	25	ps	
D _{OUTBUF}		50	ps	
		75	ps	

Note to Table 59:

Glossary

Table 60 lists the glossary for this chapter.

Table 60. Glossary (Part 1 of 4)

Letter	Subject	Definitions
Α		
В	_	_
С		
D		
E	_	
	f _{HSCLK}	Left and right PLL input clock frequency.
F	f _{HSDR}	High-speed I/O block—Maximum and minimum LVDS data transfer rate (f _{HSDR} = 1/TUI), non-DPA.
	f _{HSDRDPA}	High-speed I/O block—Maximum and minimum LVDS data transfer rate (f _{HSDRDPA} = 1/TUI), DPA.

⁽¹⁾ You can set the programmable output buffer delay in the Quartus II software by setting the Output Buffer Delay Control assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the Output Buffer Delay assignment.

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Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	-
1		
J	JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI TCK TJPSU TJ
K L M N	_	
P	PLL Specifications	Diagram of PLL Specifications (1) CLKOUT Pins Four Core Clock Reconfigurable in User Mode External Feedback Note: (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.
Q	_	-
R	R _L	Receiver differential input discrete resistor (external to the Stratix V device).
	_ <u>-</u>	1

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Table 61. Document Revision History (Part 2 of 3)

Date	Version	Changes					
		■ Added the I3YY speed grade and changed the data rates for the GX channel in Table 1.					
		■ Added the I3YY speed grade to the V _{CC} description in Table 6.					
		■ Added the I3YY speed grade to V _{CCHIP_L} , V _{CCHIP_R} , V _{CCHSSI_L} , and V _{CCHSSI_R} descriptions in Table 7.					
		■ Added 240-Ω to Table 11.					
		■ Changed CDR PPM tolerance in Table 23.					
		■ Added additional max data rate for fPLL in Table 23.					
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 25.					
		■ Added the I3YY speed grade and changed the data rates for transceiver speed grade 3 in Table 26.					
		■ Changed CDR PPM tolerance in Table 28.					
		■ Added additional max data rate for fPLL in Table 28.					
		■ Changed the mode descriptions for MLAB and M20K in Table 33.					
		■ Changed the Max value of f _{HSCLK_OUT} for the C2, C2L, I2, I2L speed grades in Table 36.					
November 2014	3.3	■ Changed the frequency ranges for C1 and C2 in Table 39.					
		■ Changed the .rbf file sizes for 5SGSD6 and 5SGSD8 in Table 47.					
		■ Added note about nSTATUS to Table 50, Table 51, Table 54.					
		■ Changed the available settings in Table 58.					
		■ Changed the note in "Periphery Performance".					
		■ Updated the "I/O Standard Specifications" section.					
		■ Updated the "Raw Binary File Size" section.					
		■ Updated the receiver voltage input range in Table 22.					
		■ Updated the max frequency for the LVDS clock network in Table 36.					
		■ Updated the DCLK note to Figure 11.					
		■ Updated Table 23 VO _{CM} (DC Coupled) condition.					
		■ Updated Table 6 and Table 7.					
		■ Added the DCLK specification to Table 55.					
		■ Updated the notes for Table 47.					
		■ Updated the list of parameters for Table 56.					
November 2013	3.2	■ Updated Table 28					
November 2013	3.1	■ Updated Table 33					
November 2013	3.0	■ Updated Table 23 and Table 28					
October 2013	2.9	■ Updated the "Transceiver Characterization" section					
		■ Updated Table 3, Table 12, Table 14, Table 19, Table 20, Table 23, Table 24, Table 28, Table 30, Table 31, Table 32, Table 33, Table 36, Table 39, Table 40, Table 41, Table 42, Table 47, Table 53, Table 58, and Table 59					
October 2013	2.8	■ Added Figure 1 and Figure 3					
		■ Added the "Transceiver Characterization" section					
		■ Removed all "Preliminary" designations.					

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